

Plasma Etching System

Offering repeatability, reliability, and low maintenance costs, the MK-II is the go-to choice for printed circuit board manufactures. This system offers technological advantages such as process temperature control and electrostatic shielding; both work in harmony to produce the most consistent, most uniform, and most reliable etch rates obtainable across an entire board's surface.



STANDARD FEATURES

Electrode Configuration	24"W x 18"D (Several Optional Configurations); 6, 8, 12, 16 and 24-Shelf Systems Available
Generator	1200W to 5000W; 13.56MHz Continuously Variable Power Supply with Automatic Matching Network
Gas Control	Two 0-2000cc Mass Flow Controllers with Low Gas Source Alarm
Control System	Color PLC-Based Touch Screen Control Interface; Stores Multiple Three-Step Recipes
Vacuum Gauge	1-2000 mT
Vacuum Pump	29CFM to 56CFM 2-Stage Direct Drive Oil Pump (Oxygen Service - Krytox Charged) with Blower
Chamber	6061-T6 Aluminum
Unit Dimensions	66" x 79" x 26"

FACILITY REQUIREMENTS

Electrical	120/208 VAC, 50/60 Hz @ 50-100Amps, 3 Phase, 5 Wire
Compressed Air Service	80-100PSI, 0.5CFM
Regulated Process Gases	15-30PSI
Cooling	Cooling Water Source for RF Generator @ 2GPM

OPTIONAL FEATURES

- Custom Vacuum Chamber or Electrode Size
- Reactive Ion Electrodes
- MHz Power Supplies with Automatic Matching Network
- PC-Based Control System
- Electrostatic Shielding
- Temperature Control System
- Dry and Oil-Driven Vacuum Pumps and Blower Boosters
- Chiller System for Dry Vacuum Pump
- Chamber and Vacuum Pump Purge Systems
- Vacuum Pump Oil Mist Eliminator
- Vacuum Pump Oil Filtration
- Automatic Vacuum Control
- Additional Digital Mass Flow Controllers
- Software Configurable Gas Steering Matrix 2x5
- Low Gas-Source Alarm
- Light Tower
- Fume Scrubber